

1.5A, 200V - 600V High Efficient Surface Mount Rectifier

FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Fast switching for high efficiency
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Switching mode converters and inverters
- Lighting application
- Snubber
- · Freewheeling application

MECHANICAL DATA

- Case: DO-214AC (SMA)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.064g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I _F	1.5	Α	
V_{RRM}	200 - 600	V	
I _{FSM}	30	Α	
T _{J MAX}	150	°C	
Package	DO-214AC (SMA)		
Configuration	Single die		









DO-214AC (SMA)



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)					
PARAMETER	SYMBOL	BYG20D	BYG20G	BYG20J	UNIT
Marking code on the device		BYG20D	BYG20G	BYG20J	
Repetitive peak reverse voltage	V_{RRM}	200	400	600	V
Reverse voltage, total rms value	$V_{R(RMS)}$	140	280	420	V
Forward current	I _F	1.5		Α	
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	30		Α	
Pulse energy in avalanche mode, non-repetitive (Inductive load switch off), L = 120mH	E _{RSM}	20		mJ	
Junction temperature	T_J		- 55 to +150		°C
Storage temperature	T _{STG}	- 55 to +150		°C	

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THERMAL PERFORMANCE				
PARAMETER	SYMBOL	ТҮР	UNIT	
Junction-to-lead thermal resistance	R _{OJL}	25	°C/W	
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	100	°C/W	

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage ⁽¹⁾	$I_F = 1.0A, T_J = 25^{\circ}C$	V	-	1.3	V
Polward voltage	$I_F = 1.5A, T_J = 25^{\circ}C$	V_F	-	1.4	V
Reverse current @ rated V _R ⁽²⁾	$T_{J} = 25^{\circ}C$	-	1	μΑ	
neverse current @ rated v _R	T _J = 100°C	l _R	-	10	μΑ
Reverse recovery time	$I_F = 0.5A, I_R = 1.0A,$ $I_{rr} = 0.25A$	t _{rr}	-	75	ns

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING	
BYG20x	DO-214AC (SMA)	7,500 / Tape & Reel	

Notes:

1. "x" defines voltage from 200V(BYG20D) to 600V(BYG20J)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

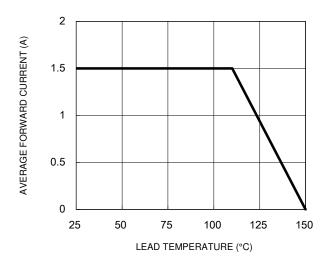


Fig.3 Typical Reverse Characteristics

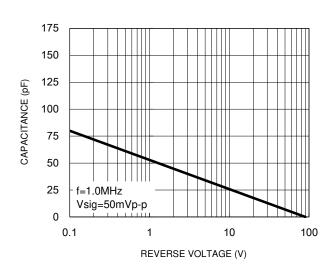
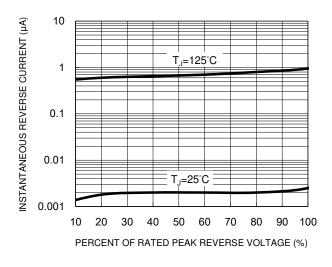


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



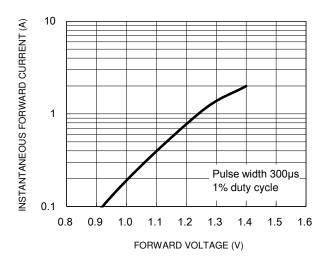
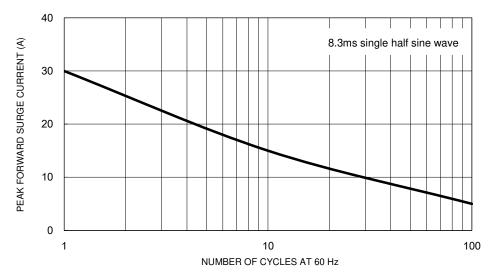


Fig.5 Maximum Non-Repetitive Forward Surge Current

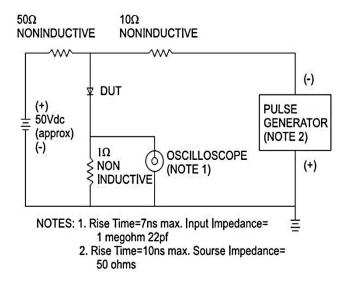


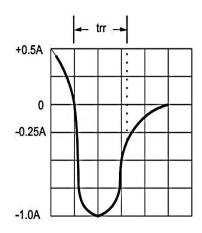
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CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram

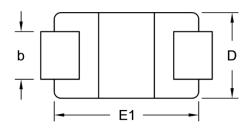


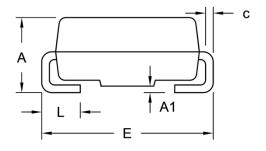




PACKAGE OUTLINE DIMENSIONS

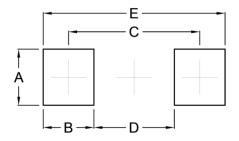
DO-214AC (SMA)





DIM.	Unit (mm)		Unit ((inch)	
Dilvi.	Min.	Max.	Min.	Max.	
Α	1.99	2.50	0.078	0.098	
A1	0.10	0.20	0.004	0.008	
b	1.27	1.58	0.050	0.062	
С	0.15	0.31	0.006	0.012	
D	2.29	2.83	0.090	0.111	
E	4.95	5.33	0.195	0.210	
E1	4.06	4.60	0.160	0.181	
L	0.90	1.41	0.035	0.056	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	1.68	0.066
В	1.52	0.060
С	3.93	0.155
D	2.41	0.095
E	5.45	0.215

MARKING DIAGRAM



= Marking Code P/N G = Green Compound

= Date Code ΥW F = Factory Code



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